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YOUR MODULE NO.:		OUR MODULE	E NO.:	T200QFE-V44	F
YOUR SPEC NO.:	OUR FULL SP	EC NO.:	FS- T200QFE-V	14-F -01	
	APPRO	VED BY			
APPR	ROVED B	Y CUSTON	/IER		

Kitronix (Dong Guan) Ltd.

No. A20, Luyi Road, Tianxin Country, Tangxia Town, Dongguan City, Guangdong Province.

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FS-T200QFE-V44-F

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PAGE 1 OF 22

T200QFE-V44-F

Product

Standard LCD Module
176 x RGB x 220 Dots
2.0" TFT LCD
Wide temperature
With white color LED backlight
With Touch Panel

Kitronix (Dong Guan) Ltd.

No. A20, Luyi Road, Tianxin Country, Tangxia Town, Dongguan City, Guangdong Province.



FS-T200QFE-V44-F

www.D23/Dec/2009om

PAGE 2 OF 22

CONTENTS

		Page No.
1.	DOCUMENT REVISION HISTORY	3
2.	GENERAL DESCRIPTION	4
3.	MECHANICAL SPECIFICATIONS	4
4.	INTERFACE SIGNALS	6
5.	ABSOLUTE MAXIMUM RATINGS	7
6.	ELECTRICAL SPECIFICATIONS	7
7.	OPTICAL CHARACTERISTICS	8
8.	TIMING CHARACTERISTICS	10
9.	RELIABILITY TEST ITEM	12
10.	SUGGESTIONS FOR USING LCD MODULES	13
11.	INSPECTION STANDARD	16
12.	PACKING(REFERENCE ONLY)	22



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Kitronix (Dong guan) Ltd. PRODUCT SPECIFICATION

FS-T200QFE-V44-F

www.**23/Dec/2009**om

PAGE 3 OF 22

1. Document revision history:

DOCUMENT REVISION	DATE	v	DESCRIPTION	PREPARED BY	APPROVED BY
01	2009.12.23	First Release.		Van Ng	



FS-T200QFE-V44-F

www.D23/Dec/2009om

PAGE 4 OF 22

2. General Description

- 2.0"(diagonal), 176 x RGB x 220 dots, 262k colors, Transmissive, TFT LCD module.
- Viewing Direction: 12 o'clock.
- Driving IC: LGDP4525B or equivalent TFT controller/driver.
- 16-bits data bus (I80 system interface).
- Logic voltage: 2.8V (typ.).
- With Touch panel.

3. Mechanical Specifications

The mechanical detail is shown in Fig. 1 and summarized in Table 1 below.

Table 1

Parameter		Specifications	Unit
Outline dimensions		37.73(W) x 51.35(H) x 3.42(D) (Exclude FPC, cables of backlight)	mm
	View area	33.89(W) x 45.1(H)	mm
	TP active area	33.49(W) x 44.7(H)	mm
Color TFT	LCD active area	31.68(W) x 39.6(H)	mm
176xRGBx220	Display format	176 x RGB x 220	dots
	Color configuration	RGB stripes	-
	Dot pitch	$0.18(RGB)(W) \times 0.18(H)$	mm
Weight		TBD	TBD



FS-T200QFE-V44-F

www.D23/Dec/2009om

PAGE 5 OF 22

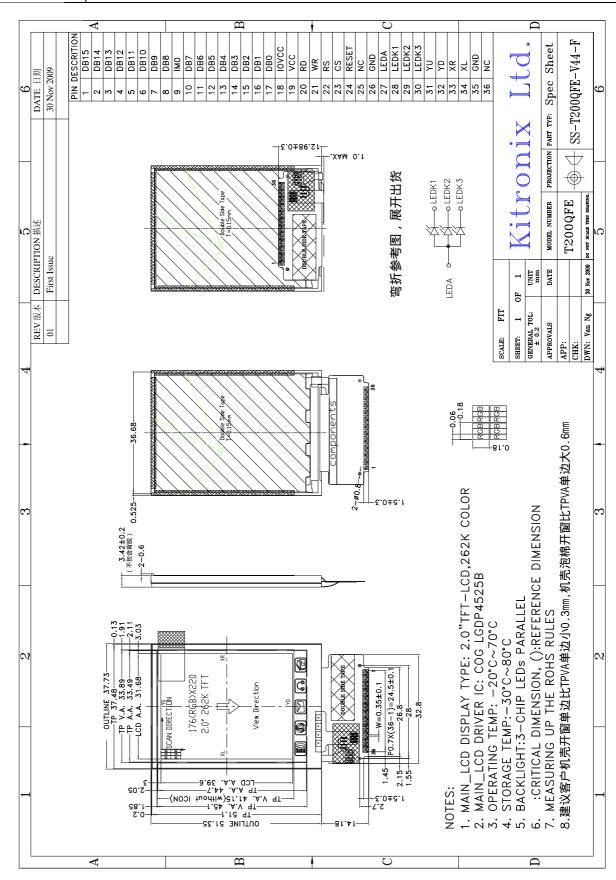


Figure 1: Outline Drawing



FS-T200QFE-V44-F

www.D23/Dec/2009om

PAGE 6 OF 22

4. Interface signals

Table 2: Pin assignment

Pin No.	Symbol	Description
1-8	[DB15-DB8]	16-bit bi-directional data bus.
9	IM0	"LOW":16 bit; "HIGH":8 bit, default: "OPEN".
10-17	[DB7-DB0]	16-bit bi-directional data bus.
18	IOVCC	A power supply for the internal logic circuit and for the I/O circuit. $VCC = 1.8 \sim 3.3V$.
19	VCC	A power supply for the internal analog circuit. $VCC = 2.2 \sim 3.3V$.
20	RD	I80 system: Serves as a read signal and reads data at the low level.
21	WR	I80 system: Serves as a write signal and writes data at the rising edge.
22	RS	Register Select Signal (H: Data, L: Instruction)
23	CS	Chip select signal. 0: chip can be accessed; 1: chip cannot be accessed.
24	RESET	Reset pin. Setting either pin low initializes the LSI. Must be reset the chip after power being supplied.
25	NC	No connection.
26	GND	Ground for the logic and analog circuit.
27	LEDA	Anode of LED backlight.
28	LEDK1	
29	LEDK2	Cathode of LED backlight.
30	LEDK3	
31	YU	
32	YD	Terminal of touch panel.
33	XR	Terminal of touch panel.
34	XL	
35	GND	Ground for the logic and analog circuit.
36	NC	No connection



FS-T200QFE-V44-F

www.D23/Dec/2009om

PAGE 7 OF 22

5. Absolute Maximum Ratings

5.1 Electrical Maximum Ratings – for IC Only

Table 3: Electrical Maximum Ratings – for IC

Parameter	Symbol	Min.	Max.	Unit	Note
Power supply voltage (VCC)	VCC	-0.3	+4.5	V	1
Power supply voltage (IOVCC)	VCC	-0.3	+4.5	V	1

Note:

- 1.VCC,GND must be maintained.
- 2. The modules may be destroyed if they are used beyond the absolute maximum ratings.

5.2 Environmental Condition

Table 4

Item	Operating temperature (Topr)		Stor temper (Tst (Not	Remark	
	Min.	Max.	Min.	Max.	
Ambient temperature	-20°C	+70°C	-30°C	+80°C	Dry
Humidity (Note 1)	80	No			
Truilliaity (Note 1)	< 50% RH for 40°	$C < Ta \le Maxin$	mum operating	temperature	condensation

Note 1: Product cannot sustain at extreme storage conditions for long time.

6. Electrical Specifications

Typical Electrical Characteristics

At Ta = 25 °C, VCC=IOVCC= 2.6V to 3.3V, GND=0V.

Table 5

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Supply voltage (analog)	VCC-GND		2.6	2.8	3.3	V
Supply voltage (logic)	IOVCC-GND		2.6	2.8	3.3	V
Supply voltage of white LED backlight	VLED =V(BL+)- V(BL-)	Forward current =45 mA Number of LED	2.9	3.2	3.5	V
Luminance (on the module surface)		dies = 3	-	150	-	cd/m ²



FS-T200QFE-V44-F

www.D23/Dec/2009om

PAGE 8 OF 22

7. Optical Characteristics

Table 7: Optical specifications

Items		Cymbol	Condition	Spe	Specifications			
Items		Symbol	Condition	Min.	in. Typ. Max.		Unit	
Contrast Ra	atio	CR		-	350	-	-	
Response T	ime	T_R		-	10	20	ms	
Response 1	IIIIC	T_{F}		-	15	20	ms	
	Red	X_R		-	0.651	-	-	
	Red	Y_R		-	0.332	-	-	
	Green	X_{G}		-	0.301	-	-	
Chromaticity	Giccii	Y_{G}		-	0.585	-	-	Note
Cinomaticity	Blue	X_{B}		-	0.133	-	-	Note
	Diuc	Y_B		-	0.136	-	-	
	White	X_{W}		-	0.309	-	-	
	vv iiitc	Y_{W}		-	0.345	-	-	
	Hor.	\$\phi 1(3 o'clock)		-	45	-		
Viewing angle		\$\phi 2(9 o'clock)	Center	-	45	-	deg.	
viewing angle	Ver.	θ2(12 o'clock)	CR=10	-	35	-	ueg.	
	V C1.	θ1(6 o'clock)		-	15	-		
NTSC ratio					61.5		%	

Note 1: Definition of Contrast Ratio (CR):

The contrast ratio can be calculated by the following expression.

Contrast Ratio (CR) = L63 / L0

L63: Luminance of gray level 63

L0: Luminance of gray level 0

CR = CR (10)

CR (X) is corresponding to the Contrast Ratio of the point X at Figure in Note 5.

Note 2: Definition of Response Time (TR, TF):

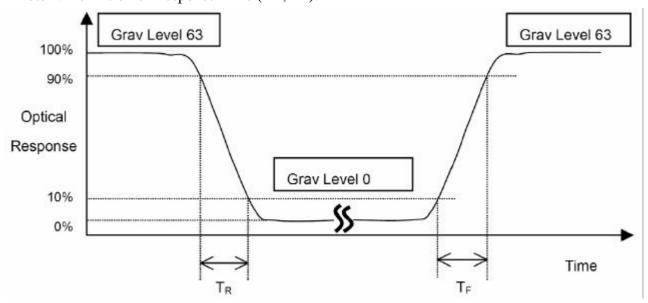


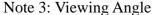
Figure 3



FS-T200QFE-V44-F

www.D23/Dec/2009om

PAGE 9 OF 22



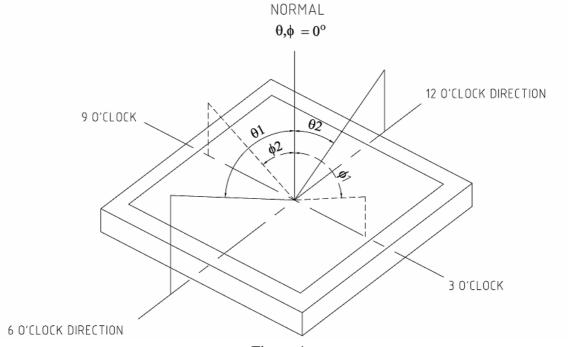


Figure 4

The above "Viewing Angle" is the measuring position with Largest Contrast Ratio; not for good image quality. View Direction for good image quality is 6 O'clock. Module maker can increase the "Viewing Angle" by applying Wide View Film.

Note 4: Measurement Set-Up:

The LCD module should be stabilized at a given temperature for 20 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting Backlight for 20 minutes in a windless room.

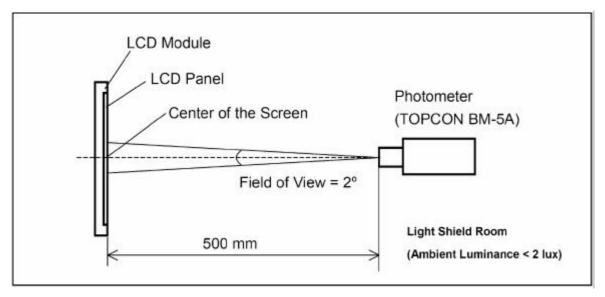


Figure 5



FS-T200QFE-V44-F

www.D23/Dec/2009om

PAGE 10 OF 22

8. Timing Characteristics

8.1 80-system Bus Interface Timing Characteristics of IC

Table 8: Normal Write Mode (VCC = IOVCC=2.4~3.3V)

Item		Symbol	Unit	Min	Тур	Max
Bus cycle time	Write	t _{CYCW}	ns	100	-	-
	Read	t _{CYCR}		250	-	-
Write "Low" level pulse width	Write	PW _{LW}	ns	40	-	-
Read "Low" level pulse width	Read	PW _{LR}		150	-	-
Write "High" level pulse width	Write	PW_{HW}	ns	30	-	-
Read "High" level pulse width	Read	PW _{HR}		100	-	-
Write/Read rise/fall time		t _{WRr,} t _{WRf}	ns	-	-	25
Setup time Write (RS	to	t _{AS}	ns	0	-	-
CSB/RW_	WRB)					
Read (RS	to	_		10	-	-
CSB/E_RD	OB)					
Address hold time		t_AH	ns	2	-	-
Write data setup time	t _{DSW}	ns	25	-	-	
Write data hold time	t _H	ns	2	-	-	
Read data delay time	t_{DDR}	ns	-	-	100	
Read data hold time		t_{DHR}	ns	5	-	-

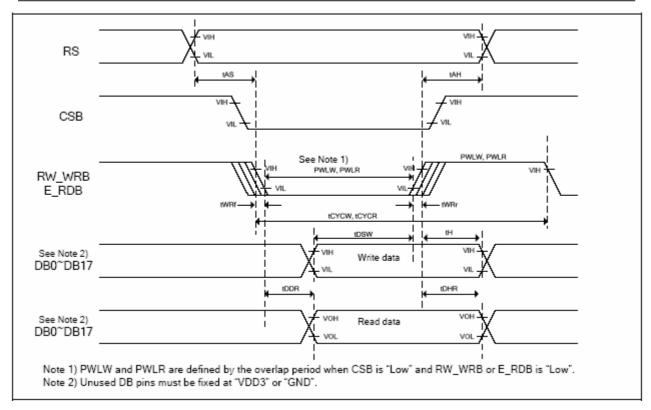


Figure 7. 80-system Bus Timing



FS-T200QFE-V44-F

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PAGE 11 OF 22

8.2 Reset Operation of IC

<u>Table 9: Reset Timing Characteristics (VCC = IOVCC=2.4~3.3V)</u>

Item	Symbol	Unit	Min.	Тур.	Max.
Reset low-level width	tRES	ms	1	-	-
Reset rise time	trRES	J\$	-	-	10

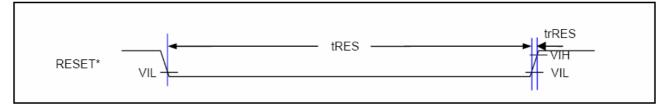


Figure 8: Reset Timing



FS-T200QFE-V44-F

PAGE 12 OF 22

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9. Reliability Test Item

Test Item	Sample Type	Test Condition	Test result determinant gist
High temperature	Normal temperature	70±3 ;96H	the inspection of
storage	Wide temperature	80±3 ;96H	appearance and function
Low temperature	Normal temperature	-20±3 ;120H	character.
storage	Wide temperature	-30±3 ;120H	
High temperature	Normal temperature	50 ±3 ,90%±3%RH;96H	
/humidity storage	Wide temperature	60 ±3 ,90%±3%RH;96H	
High temperature	Normal temperature	60±3 ;96H	no objection of the function
operation	Wide temperature	70±3 ;96H	character; no fatal objection of
Low temperature	Normal temperature	0±3 ;96H	the appearance.
operation	Wide temperature	-20±3 ;96H	
High temperature	Normal temperature	40 ±3 ,90%±3%RH;96H	
/humidity operation	Wide temperature	50 ±3 ,90%±3%RH;96H	
Temperature Shock	Normal temperature	-20±3 ,30min? 70±3 ,30	inspect the objections
		min;10cycle	appearance, function & the
			whole structure
	Wide temperature	-30 ± 3 ,30min	The inspection of appearance,
		80±3,30min;10cycle	function & the whole structure



FS-T200QFE-V44-F

www.D23/Dec/2009om

PAGE 13 OF 22

10. Suggestions for using LCD modules

10.1 Handling of LCM

- 1. The LCD screen is made of glass. Don't give excessive external shock, or drop from a high place.
- 2. If the LCD screen is damaged and the liquid crystal leaks out, do not lick and swallow. When the liquid is attach to your hand, skin, cloth etc, wash it off by using soap and water thoroughly and immediately.
- 3. Don't apply excessive force on the surface of the LCM.
- 4. If the surface is contaminated ,clean it with soft cloth. If the LCM is severely contaminated , use Isopropyl alcohol/Ethyl alcohol to clean. Other solvents may damage the polarizer . The following solvents is especially prohibited: water , ketone Aromatic solvents etc.
- 5. Exercise care to minimize corrosion of the electrode. Corrosion of the electrodes is accelerated by water droplets, moisture condensation or a current flow in a high-humidity environment.
- 6. Install the LCD Module by using the mounting holes. When mounting the LCD module make sure it is free of twisting, warping and distortion. In particular, do not forcibly pull or bend the I/O cable or the backlight cable.
- 7. Don't disassemble the LCM.
- 8. To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.
 - Be sure to ground the body when handling the LCD modules.
 - Tools required for assembling, such as soldering irons, must be properly grounded.
 - To reduce the amount of static electricity generated, do not conduct assembling and other work under dry conditions.
 - The LCD module is coated with a film to protect the display surface. Exercise care when peeling off this protective film since static electricity may be generated.
- 9. Do not alter, modify or change the the shape of the tab on the metal frame.
- 10. Do not make extra holes on the printed circuit board, modify its shape or change the positions of components to be attached.



FS-T200QFE-V44-F

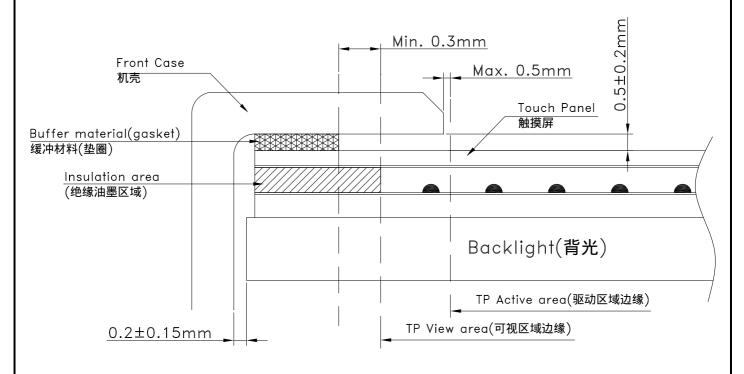
www.D23/Dec/2009om

PAGE 14 OF 22

- 11. Do not damage or modify the pattern writing on the printed circuit board.
- 12. Absolutely do not modify the zebra rubber strip (conductive rubber) or heat seal connector
- 13. Except for soldering the interface, do not make any alterations or modifications with a soldering iron.
- 14. Do not drop, bend or twist LCM.

10.2 Cautions for installing and assemabling if the module has Touch Panel

- 1. Use a buffer material (Gasket) between the touch panel and Front-case to protect damage and wrong operating. The dimension of the buffer material's edge between the TP V.A. edge is Min. 0.3mm.
- 2. We recommend to design a case that it can't over the boundary of the active area Max. 0.5mm in order to prevent an operation at outside of the active area which can't guarantee the specified durability, because operation at the outside of the active area cause serious damage of a transparent.
- 3. When design case for installing Module, you would consider give a distance about 0.2 ± 0.15 mm between the module edge to case inside.
- 4. The corners of the product are not chamfered. When positioning and fixing the product on the case, we sugguest that you would provide a R part on the conner of the case so as not to apply load on the corner of the transparent module.



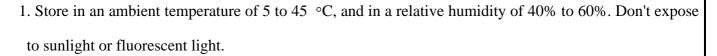


FS-T200QFE-V44-F

www.**23/Dec/2009**om

PAGE 15 OF 22

10.3 Storage



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٠,	Morage	1n a	Clean	anuironment	traa	trom	duct	2Ct1VA	COC	and	COL	7Ant
4.	Diorage	m a	CiCaii	environment	·	пош	uusi.	active	Zas.	anu	SOL	ιcπι.

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FS-T200QFE-V44-F

www.D23/Dec/2009om

PAGE 16 OF 22

11. Inspection Standard

This specification is made to be used as the standard acceptance/rejection criteria for Color mobile phone LCM with touch pannel.

11.1 Sample plan and Inspection condition

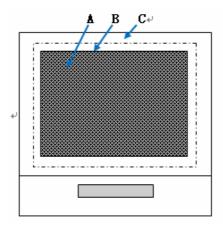
11.1.1 Sample plan

Sampling plan according to MIL-STD-105E, normal level 2 and based on:

Major defect: AQL 0.65; Minor defect: AQL 1.5. 11.1.2 Inspection condition

Viewing distance for cosmetic inspection is about 30cm with bare eyes, and under an environment of 20~40W light intensity, all directions for inspecting the sample should be within 45 against perpendicular line.

11.2 Definition of inspection zone in LCD



Inspection zones in an LCD

Zone A: character/Digit area;

Zone B: viewing area except Zone A (ZoneA+ZoneB=minimum Viewing area);

Zone C: Outside viewing area (invisible area after assembly in customer's product);

Note: As a general rule, visual defects in Zone C are permissible, when it is no trouble for quality and assembly of customer's product. Defects are classified as major defects and minor defects according to the degree of defectiveness defined herein.

11.3 Major defects and Minor defects

11.3.1 Major defects

A major defect is a defect that is likely to result in failure, or to reduce the usability of the product for its intended purpose.

11.3.1.1 Abnormal operation: modules cannot display normally;



FS-T200QFE-V44-F

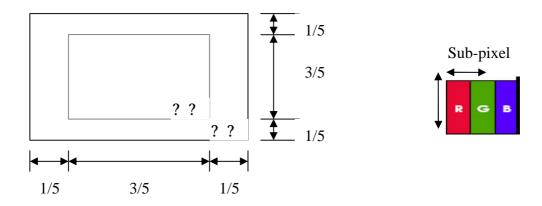
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PAGE 17 OF 22

- 11.3.1.2 Line defect;
- 11.3.1.3 There is serious distortion or sharp burr on mechanical housing;
- 11.3.1.4 Glass breakage.
- 11.3.2 Minor defects:

A minor defect is a defect that is not likely to reduce the usability of the product for its intended purpose.

- 11.3.2.1 Dot defect:
 - 11.3.2.1.1 Inspection pattern: Full white, full black, red, green and blue screens;
 - 11.3.2.1.2 Criteria:(acceptable);



- Note: 1. Dot defect is defined as the defective area of the dot area is larger than 50% of the dot area. And the bright dot defect must be visible through 5% ND filter.
 - 2. Except for the allowed numbers of adjacent dots, the distance between dot defects should be more than 3mm apart.
- 11.3.2.1.3 The definitions of the inner display area and outer display area.

11.4 Inspection standards table:

11.4.1 Major defect

Item No.	Items to be	Inspection Standard	Classification of defects
11.4.1.1	All functional defects	 No display Display abnormally Missing vertical/horizontal segment Short circuit Back-light no lighting, flickering and abnormal lighting. 	Major
11.4.1.2	Missing	Missing component	, and the second
11.4.1.3	Outline dimension	Overall outline dimension beyond the drawing is not allowed.	
11.4.1.4	linearity	No more than 1.5%	



FS-T200QFE-V44-F

www.**23/Dec/2009**om

PAGE 18 OF 22

11.4.2 Cosmetic Defect (spot defect)

Item No	Itemsto be	Inspection Standard	Classification of defects			
	Clear Spots Black and white	For dark/white spot, as F =(x +y)/2	Minor			
	Spot defect	Zone		Acceptabl	le Qty	
11.4.2.1	Pinhole,	Size(mm)	A	В	С	
	Foreign	F=0.1	Igno	ore		Minan
	Particle,	0.10< F=0.15	2		Ignore	Minor
	polarizer Dirt	0.15< F=0.20	1		ignore	
	Dirt	F > 0.20	0			
	Clear Spots TP Dirt	Zone	Acceptable Qty			
		Size(mm)	A	В	С	
11 400		F=0.1	Ignore		Ignore	3.4.
11.4.2.2		0.10< F=0.15	2			Minor
		0.15< F=0.25	1			
		F > 0.25	0			
	Dim Spots	Zone	Acceptable		le Qty	
	Circle shaped and dim edged defects	Size(mm)	A	В	С	
11 402		F=0.2	Ignore			3.4"
11.4.2.3		0.20< F=0.4	2		Ignore	Minor
		0.4< F=0.6	1		ignore	
		F> 0.6	0			
		dot =sub-pixel				-
		Acceptable Qty		e Qty		
			I		II	
11.4.2.4	Dot defect	Bright dot	0		2	Minor
		Dark dot	1		2	
		The distance of two				
11 10 0	D. C (1)	1.6	7 JIIII / JIIIII			

11.4.3 Cosmetic Defect (linear defect)

Item No	Items to be		Classification of defects					
		Si	ze(mm)	Ac	ty			
	Line defect	Line defect	I (I - m-4h) W(W(14h)			zone		
	Black line,	L(Length)	W(Width)	A	В	С		
11.4.3.1	White line, Foreign material on polarizer	Ignore W=0.02		Ignore			Minor	
		L=3.0	0.02< W=0.03	2		Ionono		
		L=2.0	0.03< W=0.05			Ignore		
			W> 0.05	Define as spot defect				



FS-T200QFE-V44-F

www.**23/Dec/2009**om

PAGE 19 OF 22

		The line can b	e seen at	fter mobile	phone in	the op	erating con	dition:				
		Siz	ze(mm))		Aco	ceptable Q	Oty				
	Foreign	L(Length)	(Length) W(W		zone							
11.4.3.2	Material on TP film	Z(Zengui)			A		В	C	Minor			
	1 P film	Ignore	W=0.0	03		Igno	ore					
		L=3.0	0.03 <	W=0.05		3		Ignore				
			W> 0	0.05	Define	as sp	ot defect					
	Dim line	If the scratch coperating cond be seen only in the following.	lition, ju	dge by the	line defec	t of 1	1.4.3.1. If th	ne scratch can				
	defect Polarizer	defect Si		(mm) Acceptable		ceptable Ç	Q ty					
11.4.3.3		I (I anath)	Length) W(Width) gnore W=0.02		zone		-	Minor				
11.7.5.5		L(Length)			A		В	C	Willion			
		Ignore			Ignore							
		L=3.0	0.02<	W=0.03		2		Ignore				
					L=2.0	0.03<	W=0.05		1		Ignore	
		W> 0.05		Define as spot defect								
		Air bubbles	betwee	en glass &	polariz	er						
					Acceptable Qty							
	D 1 '			A		В		С				
11.4.3.4	Polarize Air	F=0.2			Igno	e			Minor			
	bubble	0.20< F=	0.3		2			Ionono				
		0.3< F=0	.5		1			Ignore				
		F > 0.5			0							

11.4.4 Chipping Defect

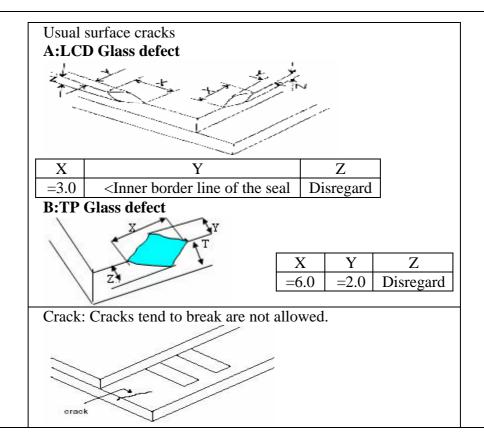
Item No	Items to be	Inspection Standard			Classification of defects
11.4.4.1	Glass defect	Chips on corner A:LCD Glass defect Notes: S=contact pad length Chips on the corner of terminal shall no ITO pad or expose perimeter seal. B:TP Glass defect T Z	$\begin{array}{ c c }\hline X & Y \\ \hline =0.2 & =S \\ \hline \text{t be allowed to exter} \\ \hline \hline X & Y \\ \hline =3.0 & =3.0 \\ \hline \end{array}$	Z Disregard end into the Z Disregard	Minor



FS-T200QFE-V44-F

www.**23/Dec/2009**om

PAGE 20 OF 22



11.4.5 Parts Defect

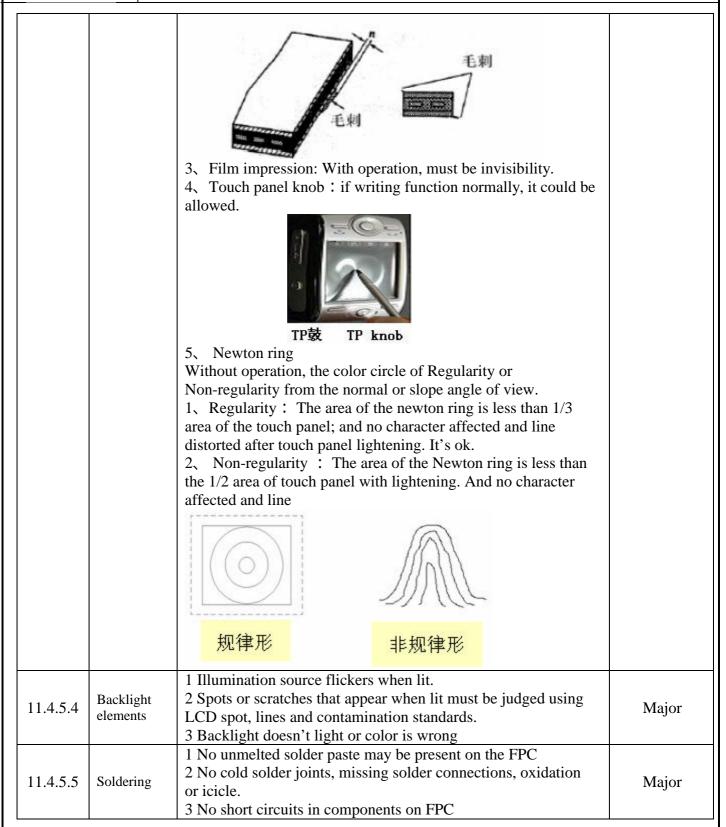
11111010	tis Defect	,	
Item No	Items to be	Inspection Standard	Classification of defects
11.4.5.1	Parts contra position	 Not allow IC and FPC/heat-seal lead width is more than beyond lead pattern. Not allow chip or solder component is off center more than of the pad outline. 	Major
11.4.5.2	SMT	According to the <acceptability assemblies="" electronic="" of="">IPC-A-610C class 2 standard. Component missing or function defect are Major defect, the others are Minor defect.</acceptability>	Major
11.4.5.3	TP Defect	1、Pattern font: Pattern fonts are clear and symmetrical, pattern fonts filter lightly are allowed; The fort line is not allow to thinner or thicker than 1/3 of normal size, and swing is not more than 0.1mm. the line is smooth and not broken. 图案字体 Pattern font 2、The wing forward in the side of Visual Area: The length of wing forward inside of the Visual Area: n=0.2mm; Not excess 3 point, and the distance D=20mm _o	Major



FS-T200QFE-V44-F

www.**D23/Dec/2009**om

PAGE 21 OF 22





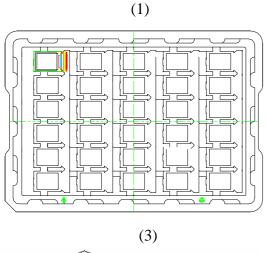
FS-T200QFE-V44-F

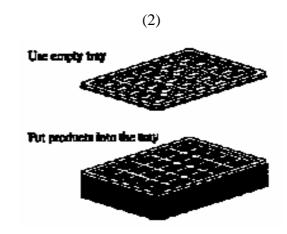
www.D23/Dec/2009om

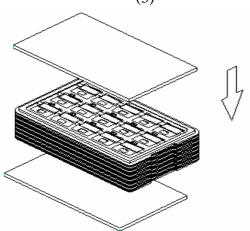
PAGE 22 OF 22

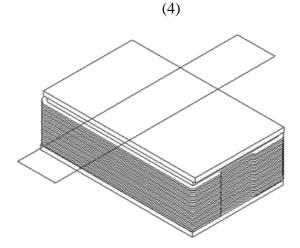
12. Packing (Reference only)

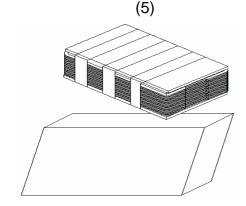
Packing Method

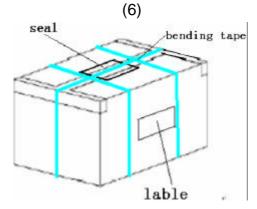












- 1. Put module into tray cavity:
- 2. Tray stacking
- 3. Put 1 cardboard under the tray stack and 1 cardboard above:
- 4. Fix the cardboard to the tray stack with adhesive tape:
- 5. Put the tray stack into carton.
- 6. Carton sealing with adhesive tape.

- END -